

# SN54157, SN54LS157, SN54LS158, SN54S157, SN54S158, SN74157, SN74LS157, SN74LS158, SN74S157, SN74S158 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

MARCH 1974 — REVISED MARCH 1988

- Buffered Inputs and Outputs
- Three Speed/Power Ranges Available

TYPES	TYPICAL AVERAGE PROPAGATION TIME	TYPICAL POWER DISSIPATION
'157	9 ns	150 mW
'LS157	9 ns	49 mW
'S157	5 ns	250 mW
'LS158	7 ns	24 mW
'S158	4 ns	195 mW

**applications**

- Expand Any Data Input Point
- Multiplex Dual Data Buses
- Generate Four Functions of Two Variables (One Variable Is Common)
- Source Programmable Counters

**description**

These monolithic data selectors/multiplexers contain inverters and drivers to supply full on-chip data selection to the four output gates. A separate strobe input is provided. A 4-bit word is selected from one of two sources and is routed to the four outputs. The '157, 'LS157, and 'S157 present true data whereas the 'LS158 and 'S158 present inverted data to minimize propagation delay time.

FUNCTION TABLE

STROBE $\bar{G}$	INPUTS		OUTPUT Y		
	SELECT $\bar{A}/\bar{B}$	A	B	'157, 'LS157, 'S157	'LS158 'S158
H	X	X	X	L	H
L	L	L	X	L	H
L	L	H	X	H	L
L	H	X	L	L	H
L	H	X	H	H	L

H = high level, L = low level, X = irrelevant

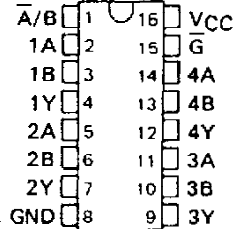
**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)**

Supply voltage, $V_{CC}$ (See Note 1)	7 V
Input voltage: '157, 'S158	5.5 V
'LS157, 'LS158	7 V
Operating free-air temperature range: SN54'	-55°C to 125°C
SN74'	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

SN54157, SN54LS157, SN54S157,  
SN54LS158, SN54S158 . . . J OR W PACKAGE  
SN74157 . . . N PACKAGE  
SN74LS157, SN74S157,  
SN74LS158, SN74S158 . . . D OR N PACKAGE

(TOP VIEW)



SN54LS157, SN54S157, SN54LS158,  
SN54S158 . . . FK PACKAGE

(TOP VIEW)



NC - No internal connection

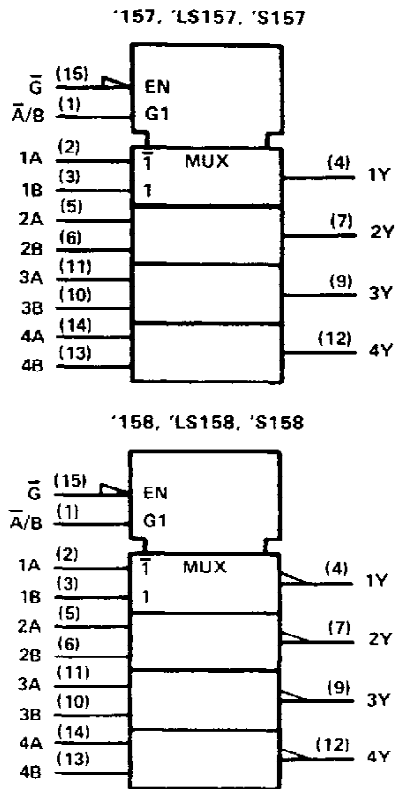
PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



POST OFFICE BOX 655812 • DALLAS, TEXAS 75265

**SN54157, SN54LS157, SN54LS158, SN54S157, SN54S158,  
SN74157, SN74LS157, SN74LS158, SN74S157, SN74S158  
QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS**

logic symbols†



logic diagram (positive logic)



† These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

schematics of inputs and outputs



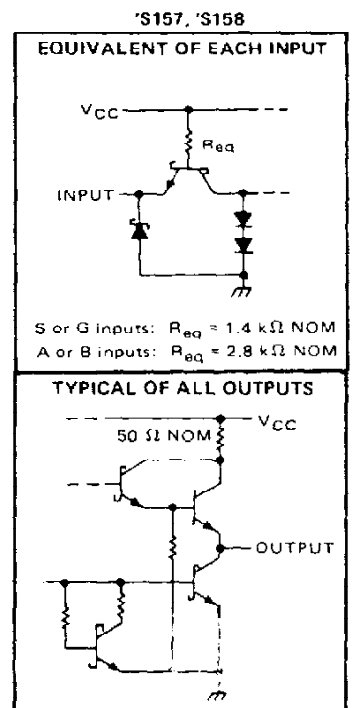
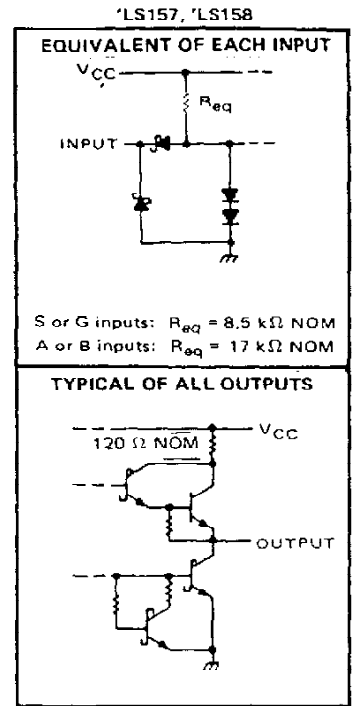
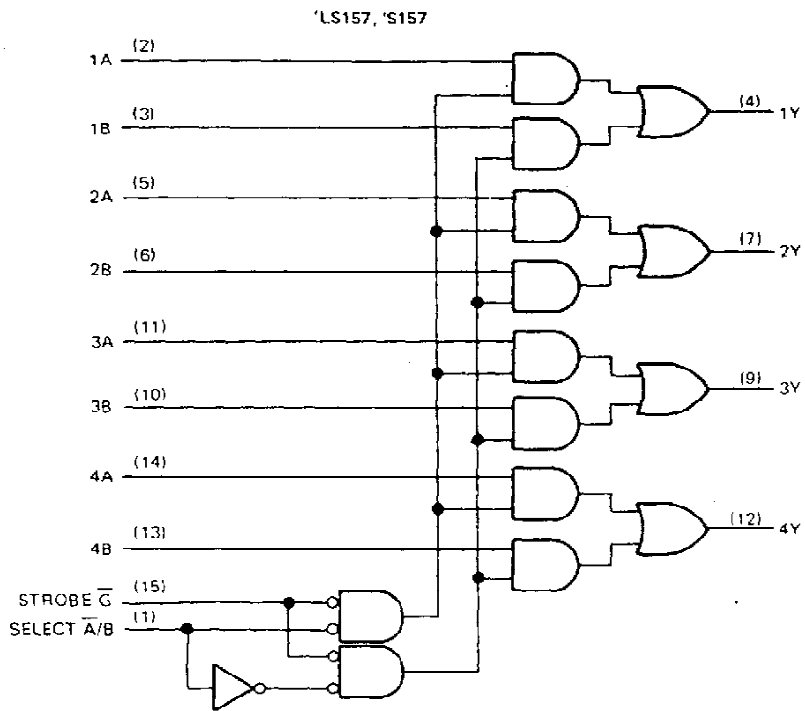
**TEXAS  
INSTRUMENTS**

POST OFFICE BOX 635012 • DALLAS, TEXAS 75265

# SN54LS157, SN54LS158, SN54S157, SN54S158, SN74LS157, SN74LS158, SN74S157, SN74S158 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

logic diagrams (positive logic)

schematics of inputs and outputs



Pin numbers shown are for D, J, N, and W packages.

**TEXAS  
INSTRUMENTS**

POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

# SN54157, SN74157 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

## recommended operating conditions

	SN54157			SN74157			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, $V_{CC}$	4.5	5	5.5	4.75	5	5.25	V
High-level output current, $I_{OH}$			-800			-800	$\mu$ A
Low-level output current, $I_{OL}$			16			16	mA
Operating free-air temperature, $T_A$	-55		125	0		70	$^{\circ}$ C

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54157			SN74157			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
$V_{IH}$ High-level input voltage		2			2			V
$V_{IL}$ Low-level input voltage				0.8			0.8	V
$V_{IK}$ Input clamp voltage	$V_{CC} = \text{MIN}$ , $I_I = -12 \text{ mA}$			-1.5			-1.5	V
$V_{OH}$ High-level output voltage	$V_{CC} = \text{MIN}$ , $V_{IH} = 2 \text{ V}$ , $V_{IL} = 0.8 \text{ V}$ , $I_{OH} = -800 \mu\text{A}$	2.4	3.4		2.4	3.4		V
$V_{OL}$ Low-level output voltage	$V_{CC} = \text{MIN}$ , $V_{IH} = 2 \text{ V}$ , $V_{IL} = 0.8 \text{ V}$ , $I_{OL} = 16 \text{ mA}$		0.2	0.4		0.2	0.4	V
$I_I$ Input current at maximum input voltage	$V_{CC} = \text{MAX}$ , $V_I = 5.5 \text{ V}$			1			1	mA
$I_{IH}$ High-level input current	$V_{CC} = \text{MAX}$ , $V_I = 2.4 \text{ V}$			40			40	$\mu$ A
$I_{IL}$ Low level input current	$V_{CC} = \text{MAX}$ , $V_I = 0.4 \text{ V}$			-1.6			-1.6	mA
$I_{OS}$ Short-circuit output current‡	$V_{CC} = \text{MAX}$	-20		-55	-18		-55	mA
$I_{CC}$ Supply current	$V_{CC} = \text{MAX}$ . See Note 2		30	48		30	48	mA

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

§Not more than one output should be shorted at a time and duration of short-circuit should not exceed one second.

NOTE 2:  $I_{CC}$  is measured with 4.5 V applied to all inputs and all outputs open.

## switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

PARAMETER¶	FROM (INPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$t_{PLH}$	Data	$C_L = 15 \mu\text{F}$ , $R_L = 400 \Omega$ , See Note 3		9	14	ns
$t_{PHL}$				9	14	
$t_{PLH}$	Strobe $\bar{G}$			13	20	ns
$t_{PHL}$				14	21	
$t_{PLH}$	Select $\bar{A}/\bar{B}$			15	23	ns
$t_{PHL}$				18	27	

¶ $t_{PLH}$  = propagation delay time, low-to-high-level output

$t_{PHL}$  = propagation delay time, high-to-low-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

TEXAS  
INSTRUMENTS

POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

## SN54LS157, SN54LS158, SN74LS157, SN74LS158 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

### recommended operating conditions

		SN54LS'			SN74LS'			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
I <sub>OH</sub>	High-level output current			-400			-400	μA
I <sub>OL</sub>	Low-level output current			4			8	mA
T <sub>A</sub>	Operating free-air temperature	-55		125	0		70	°C

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54LS'			SN74LS'			UNIT	
		MIN	TYP‡	MAX	MIN	TYP‡	MAX		
V <sub>IH</sub>	High-level input voltage	2			2			V	
V <sub>IL</sub>	Low-level input voltage			0.7			0.8	V	
V <sub>IK</sub>	Input clamp voltage	V <sub>CC</sub> - MIN, I <sub>I</sub> = -18 mA		-1.5			-1.5	V	
V <sub>OH</sub>	High-level output voltage	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, V <sub>IL</sub> = MAX, I <sub>OH</sub> = -400 μA		2.5	3.4		2.7	3.4	V
V <sub>OL</sub>	Low-level output voltage	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, V <sub>IL</sub> = MAX		I <sub>OL</sub> = 4 mA	0.25	0.4	0.25	0.4	V
				I <sub>OL</sub> = 8 mA			0.35	0.5	
I <sub>I</sub>	Input current at maximum input voltage	A/B or $\bar{G}$ A or B	V <sub>CC</sub> = MAX, V <sub>I</sub> = 7 V			0.2		0.2	mA
						0.1		0.1	
I <sub>IH</sub>	High-level input current	A/B or $\bar{G}$ A or B	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.7 V			40		40	μA
						20		20	
I <sub>IL</sub>	Low-level input current	A/B or $\bar{G}$ A or B	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.4 V			-0.8		-0.8	mA
						-0.4		-0.4	
I <sub>OS</sub>	Short-circuit output current§	V <sub>CC</sub> = MAX		-20		-100	-20	-100	mA
I <sub>CC</sub>	Supply current	V <sub>CC</sub> = MAX, See Note 2		'LS157	9.7	16	9.7	16	mA
				'LS158	4.8	8	4.8	8	
				'LS158	6.5	11	6.5	11	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

§ Not more than one output should be shorted at a time and duration of short circuit should not exceed one second.

NOTE 2: I<sub>CC</sub> is measured with 4.5 V applied to all inputs and all outputs open.

### switching characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C

PARAMETER¶	FROM (INPUT)	TEST CONDITIONS	'LS157			'LS158			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
t <sub>PLH</sub>	Data	C <sub>L</sub> = 15 pF, R <sub>L</sub> = 2 kΩ, See Note 3	9	14		7	12	ns	
t <sub>PHL</sub>			9	14		10	15		
t <sub>PLH</sub>	Strobe $\bar{G}$		13	20		11	17	ns	
t <sub>PHL</sub>			14	21		18	24		
t <sub>PLH</sub>	Select A/B		15	23		13	20	ns	
t <sub>PHL</sub>			18	27		16	24		

¶ t<sub>PLH</sub> = propagation delay time, low-to-high-level output

t<sub>PHL</sub> = propagation delay time, high-to-low-level output

NOTE 3: Load circuits and voltage diagrams are shown in Section 1.

  
**TEXAS  
INSTRUMENTS**

POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

# SN54S157, SN54S158, SN74S157, SN74S158 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

recommended operating conditions

	SN54S157 SN54S158			SN74S157 SN74S158			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, $V_{CC}$	4.5	5	5.5	4.75	5	5.25	V
High-level output current, $I_{OH}$			-1			-1	mA
Low-level output current, $I_{OL}$			20			20	mA
Operating free-air temperature, $T_A$	-55		125	0		70	$^{\circ}$ C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54S157 SN74S157			SN54S158 SN74S158			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
$V_{IH}$ High-level input voltage		2			2			V
$V_{IL}$ Low-level input voltage				0.8			0.8	V
$V_{IK}$ Input clamp voltage	$V_{CC} = \text{MIN}, I_I = -18 \text{ mA}$			-1.2			-1.2	V
$V_{OH}$ High-level output voltage	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V},$ $V_{IL} = 0.8 \text{ V}, I_{OH} = -1 \text{ mA}$	Series 54S	2.5	3.4	Series 74S	2.5	3.4	V
		Series 74S	2.7	3.4	Series 74S	2.7	3.4	
$V_{OL}$ Low-level output voltage	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V},$ $V_{IL} = 0.8 \text{ V}, I_{OL} = 20 \text{ mA}$			0.5			0.5	V
$I_I$ Input current at maximum input voltage	$V_{CC} = \text{MAX}, V_I = 5.5 \text{ V}$			1			1	mA
$I_{IH}$ High-level input current	$\overline{A/B}$ or $\overline{G}$			100			100	$\mu$ A
	A or B			50			50	
$I_{IL}$ Low-level input current	$\overline{A/B}$ or $\overline{G}$			-4			-4	mA
	A or B			-2			-2	
$I_{OS}$ Short-circuit output current §	$V_{CC} = \text{MAX}$			-40			-100	mA
$I_{CC}$ Supply current	$V_{CC} = \text{MAX},$ All inputs at 4.5 V, See Note 2			50			39	mA
	$V_{CC} = \text{MAX},$ A inputs at 4.5 V, B,G,S, inputs at 0 V, See Note 2						81	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at  $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$ .

§ Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

Note 2:  $I_{CC}$  is measured with all outputs open.

switching characteristics,  $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$

PARAMETER ¶	FROM (INPUT)	TEST CONDITIONS	SN54S157 SN74S157			SN54S158 SN74S158			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
$t_{PLH}$	Data	$C_L = 15 \text{ pF},$ $R_L = 280 \Omega,$ See Note 3	5	7.5		4	6	ns	
$t_{PHL}$			4.5	6.5		4	6		
$t_{PLH}$	Strobe $\overline{G}$		8.5	12.5		6.5	11.5	ns	
$t_{PHL}$			7.5	12		7	12		
$t_{PLH}$	Select $\overline{A/B}$		9.5	15		8	12	ns	
$t_{PHL}$			9.5	15		8	12		

¶  $t_{PLH}$  = propagation delay time, low-to-high-level output

¶  $t_{PHL}$  = propagation delay time, high-to-low-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

TEXAS  
INSTRUMENTS

POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
76002012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	76002012A SNJ54LS 157FK	<a href="#">Samples</a>
7600201EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7600201EA SNJ54LS157J	<a href="#">Samples</a>
7600201FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7600201FA SNJ54LS157W	<a href="#">Samples</a>
76033012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	76033012A SNJ54LS 158FK	<a href="#">Samples</a>
7603301EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7603301EA SNJ54LS158J	<a href="#">Samples</a>
7603301FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7603301FA SNJ54LS158W	<a href="#">Samples</a>
JM38510/07903BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07903BEA	<a href="#">Samples</a>
JM38510/07903BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07903BFA	<a href="#">Samples</a>
JM38510/07904BEA	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
JM38510/07904BFA	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI	-55 to 125		
JM38510/30903B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30903B2A	<a href="#">Samples</a>
JM38510/30903BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30903BEA	<a href="#">Samples</a>
JM38510/30903BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30903BFA	<a href="#">Samples</a>
M38510/07903BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07903BEA	<a href="#">Samples</a>
M38510/07903BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07903BFA	<a href="#">Samples</a>
M38510/30903B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30903B2A	<a href="#">Samples</a>
M38510/30903BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30903BEA	<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
M38510/30903BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30903BFA	<a href="#">Samples</a>
SN54157J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54157J	<a href="#">Samples</a>
SN54LS157J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS157J	<a href="#">Samples</a>
SN54LS158J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS158J	<a href="#">Samples</a>
SN54S157J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54S157J	<a href="#">Samples</a>
SN54S158J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
SN74157N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74157N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS157D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS157	<a href="#">Samples</a>
SN74LS157DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS157	<a href="#">Samples</a>
SN74LS157DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS157	<a href="#">Samples</a>
SN74LS157DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS157	<a href="#">Samples</a>
SN74LS157DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS157	<a href="#">Samples</a>
SN74LS157DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS157	<a href="#">Samples</a>
SN74LS157N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS157N	<a href="#">Samples</a>
SN74LS157N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS157NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS157N	<a href="#">Samples</a>
SN74LS157NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS157	<a href="#">Samples</a>
SN74LS157NSRE4	ACTIVE	SO	NS	16		TBD	Call TI	Call TI	0 to 70		<a href="#">Samples</a>
SN74LS157NSRG4	ACTIVE	SO	NS	16		TBD	Call TI	Call TI	0 to 70		<a href="#">Samples</a>
SN74LS158D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS158	<a href="#">Samples</a>



Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS158DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS158	<a href="#">Samples</a>
SN74LS158DG4	ACTIVE	SOIC	D	16		TBD	Call TI	Call TI	0 to 70		<a href="#">Samples</a>
SN74LS158DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS158	<a href="#">Samples</a>
SN74LS158DRE4	ACTIVE	SOIC	D	16		TBD	Call TI	Call TI	0 to 70		<a href="#">Samples</a>
SN74LS158DRG4	ACTIVE	SOIC	D	16		TBD	Call TI	Call TI	0 to 70		<a href="#">Samples</a>
SN74LS158N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS158N	<a href="#">Samples</a>
SN74LS158N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS158NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS158N	<a href="#">Samples</a>
SN74LS158NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS158	<a href="#">Samples</a>
SN74LS158NSRE4	ACTIVE	SO	NS	16		TBD	Call TI	Call TI	0 to 70		<a href="#">Samples</a>
SN74LS158NSRG4	ACTIVE	SO	NS	16		TBD	Call TI	Call TI	0 to 70		<a href="#">Samples</a>
SN74S157N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70	SN74S157N	
SN74S157N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74S158D	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	0 to 70		
SN74S158DR	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	0 to 70		
SN74S158N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74S158N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SNJ54157J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54157J	<a href="#">Samples</a>
SNJ54157W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54157W	<a href="#">Samples</a>
SNJ54LS157FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	76002012A SNJ54LS 157FK	<a href="#">Samples</a>
SNJ54LS157J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7600201EA SNJ54LS157J	<a href="#">Samples</a>
SNJ54LS157W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7600201FA SNJ54LS157W	<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54LS158FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	76033012A SNJ54LS 158FK	<a href="#">Samples</a>
SNJ54LS158J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7603301EA SNJ54LS158J	<a href="#">Samples</a>
SNJ54LS158W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7603301FA SNJ54LS158W	<a href="#">Samples</a>
SNJ54S157FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54S 157FK	<a href="#">Samples</a>
SNJ54S157J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S157J	<a href="#">Samples</a>
SNJ54S157W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S157W	<a href="#">Samples</a>
SNJ54S158FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	-55 to 125		
SNJ54S158J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
SNJ54S158W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI	-55 to 125		

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF SN54157, SN54LS157, SN54LS158, SN54S157, SN54S158, SN74157, SN74LS157, SN74LS158, SN74S157, SN74S158 :**

- Catalog: [SN74157](#), [SN74LS157](#), [SN74LS158](#), [SN74S157](#), [SN74S158](#)
- Military: [SN54157](#), [SN54LS157](#), [SN54LS158](#), [SN54S157](#), [SN54S158](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS157DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS158DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS158NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS157DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS158DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS158NSR	SO	NS	16	2000	367.0	367.0	38.0

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

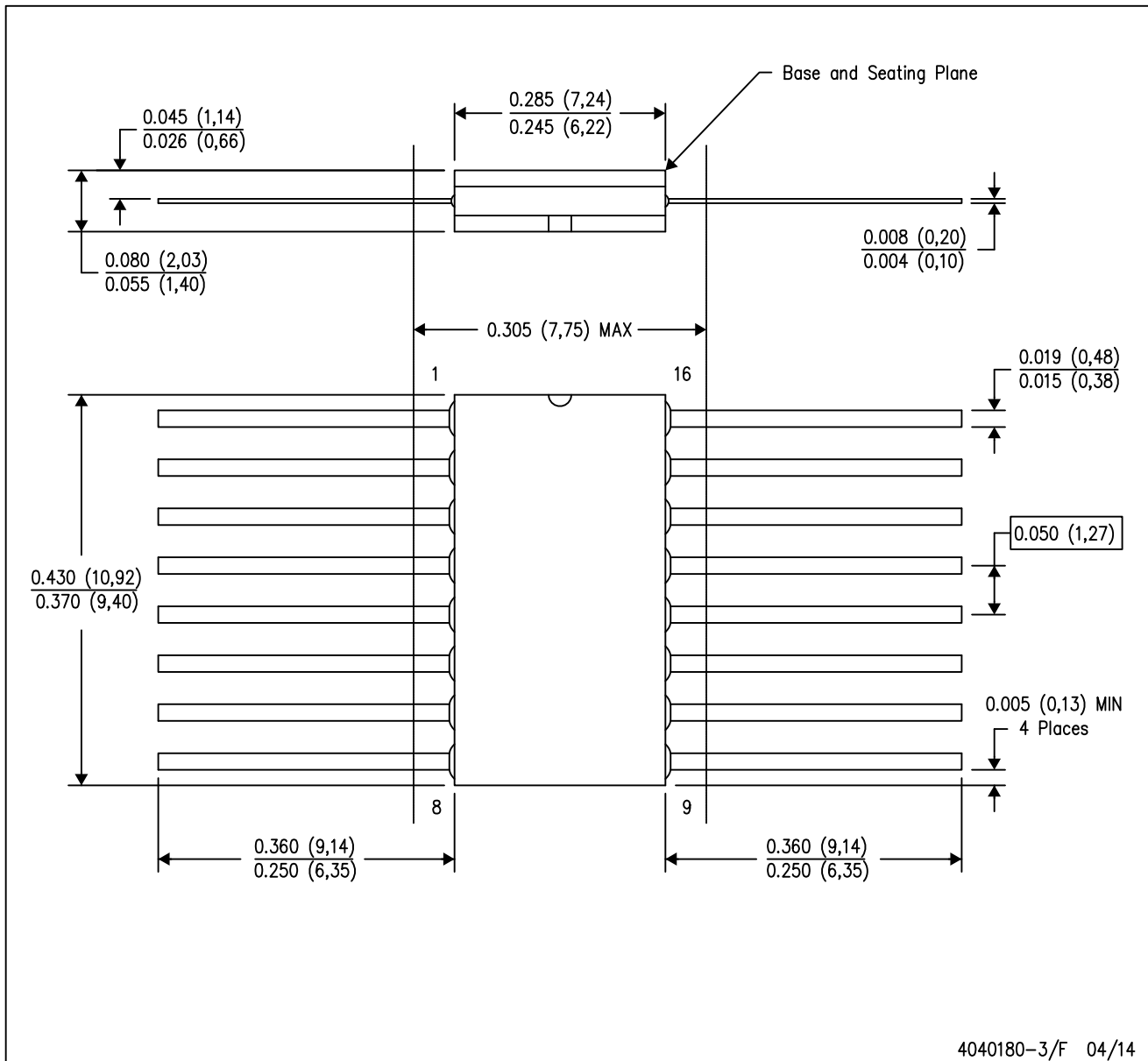


4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP2-F16

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - Falls within JEDEC MS-004



N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

### Products

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Applications Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>

### Applications

Automotive and Transportation	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Space, Avionics and Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
Video and Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>

### TI E2E Community

[e2e.ti.com](http://e2e.ti.com)